Bill of Materials

	SCK1	SK3	Remarks
Core Material	Kinsus/Samsung BT/HL-832	Kinsus/Samsung BT/HL-832	Same BOM
Die Attach	Ablestik 2025D (bottom die) Loctite/Hysol QMI536 (spacer) Ablestik 2025M (top die) Ablestik 2000 (Die Attach) Hereaus 96.5Sn/3.5Ag (Discrete Component Attach) Ablestik ATB225 (bottom die) Ablestik ATB120 (spacer) Ablestik ATB120 (top die)	Ablestik 2025D (bottom die) Loctite/Hysol QMI536 (spacer) Ablestik 2025M (top die) Ablestik 2000 (Die Attach) Hereaus 96.5Sn/3.5Ag (Discrete Component Attach) Ablestik ATB225 (bottom die) Ablestik ATB120 (spacer) Ablestik ATB120 (top die)	
Wire type	Gold MKE R 2N	Gold MKE R 2N	
Mold Compound	Sumitomo EME-G770LC Sumitomo EME-G760C Sumitomo EME-G760SYA	Sumitomo EME-G770LC Sumitomo EME-G760C Sumitomo EME-G760SYA	
Lead Finish	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu	

Qualification Result Summary for CSP_BGA at STATS ChipPAC Korea Plant 3

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 32	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC *JESD22-A118*	3 x 32	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	PASS
Electrostatic Discharge *Field Induced Charge Device Model*	JEDEC *JESD22-C101*	3/voltage	PASS ±500V

*Preconditioned per JEDEC/IPC J-STD-020